Preferred Device

# **Sensitive Gate Silicon Controlled Rectifiers**

# **Reverse Blocking Thyristors**

Designed for high volume, low cost, industrial and consumer applications such as motor control, process control, temperature, light and speed control.

#### **Features**

- Small Size
- Passivated Die for Reliability and Uniformity
- Low Level Triggering and Holding Characteristics
- Surface Mount Lead Form Case 369C
- Epoxy Meets UL 94, V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V Machine Model, C > 400 V

### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) (T <sub>J</sub> = -40 to 110°C, Sine Wave, 50 to 60 Hz, Gate Open) MCR716 MCR718	V <sub>DRM,</sub> V <sub>RRM</sub>	<b>400</b> 600	V
On–State RMS Current (180° Conduction Angles; T <sub>C</sub> = 90°C)	I <sub>T(RMS)</sub>	4.0	Α
Average On–State Current (180° Conduction Angles; T <sub>C</sub> = 90°C)	I <sub>T(AV)</sub>	2.6	Α
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T <sub>J</sub> = 110°C)	I <sub>TSM</sub>	25	A
Circuit Fusing Consideration (t = 8.3 msec)	l <sup>2</sup> t	2.6	A <sup>2</sup> sec
Forward Peak Gate Power (Pulse Width ≤ 1.0 μsec, T <sub>C</sub> = 90°C)	P <sub>GM</sub>	0.5	W
Forward Average Gate Power (t = 8.3 msec, T <sub>C</sub> = 90°C)	P <sub>G(AV)</sub>	0.1	W
Forward Peak Gate Current (Pulse Width ≤ 1.0 μsec, T <sub>C</sub> = 90°C)	I <sub>GM</sub>	0.2	Α
Operating Junction Temperature Range	TJ	-40 to +110	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

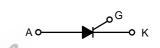
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

 V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



http://onsemi.com

# SCRs 4.0 AMPERES RMS 400 – 600 VOLTS



MARKING DIAGRAM



DPAK CASE 369C STYLE 4



Y = Year WW = Work Week x = 6 or 8

PIN ASSIGNMENT				
1	Cathode			
2	Anode			
3	Gate			
4	Anode			

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	3.0	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	80	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	T <sub>L</sub>	260	°C

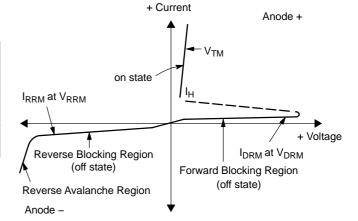
#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Peak Repetitive Forward or Reverse Blocking Current; $R_G$ ( $V_{AK}$ = Rated $V_{DRM}$ or $V_{RRM}$ )	$T_C = 1 \text{ k}\Omega \text{ (Note 3)}$ $T_C = 25^{\circ}\text{C}$ $T_C = 110^{\circ}\text{C}$	I <sub>DRM</sub> I <sub>RRM</sub>	- -	_ _	10 200	μΑ
ON CHARACTERISTICS						
Peak Reverse Gate Blocking Voltage (I <sub>GR</sub> = 10 μA)		$V_{RGM}$	10	12.5	18	V
Peak Reverse Gate Blocking Current (V <sub>GR</sub> = 10 V)		I <sub>RGM</sub>	-	-	1.2	μΑ
Peak Forward On–State Voltage (Note 4) (I <sub>TM</sub> = 5.0 A Peak) (I <sub>TM</sub> = 8.2 A Peak)		V <sub>TM</sub>	r_	1.3 1.5	1.5 2.2	V
Gate Trigger Current (Continuous dc) (Note 5) (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 30 Ohms)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	I <sub>GT</sub>	1.0 -	25 -	75 300	μΑ
Gate Trigger Voltage (Continuous dc) (Note 5) (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 30 Ohms)	$T_C = 25$ °C $T_C = -40$ °C $T_C = 110$ °C	V <sub>GT</sub>	0.3 - 0.2	0.55 - -	0.8 1.0 –	V
Holding Current (Note 3) (V <sub>D</sub> = 12 Vdc, Initiating Current = 200 mA, Gate Open)	T <sub>C</sub> = 25°C	l <sub>Η</sub>	0.4	1.0	5.0 10	mA
					5.0 10	mA
					5.0	μs
					_	V/μs
					100	A/μs
						1

vith a negative voltage y such that the voltage

#### **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Off-State Forward Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
$V_{RRM}$	Peak Repetitive Off-State Reverse Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
$V_{TM}$	Peak On-State Voltage
I <sub>H</sub>	Holding Current



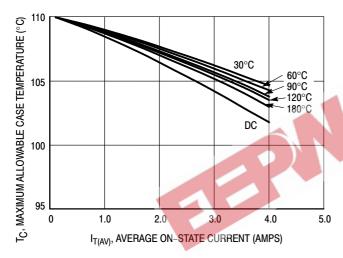


Figure 1. Average Current Derating

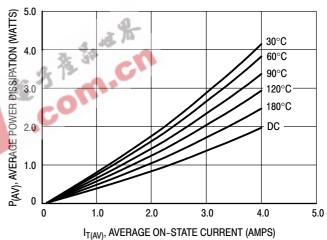


Figure 2. On-State Power Dissipation

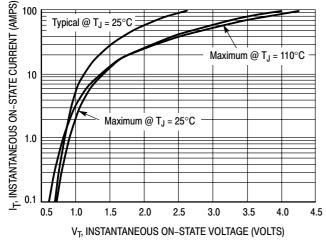
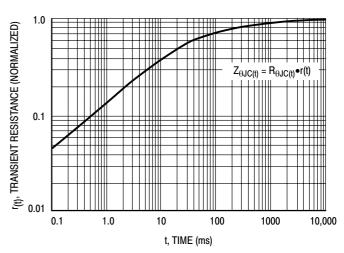


Figure 3. On-State Characteristics



**Figure 4. Transient Thermal Response** 

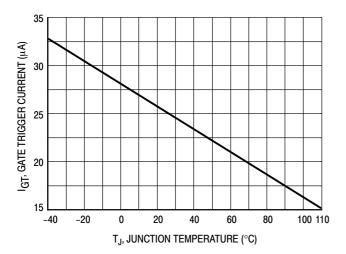


Figure 5. Typical Gate Trigger Current versus Junction Temperature

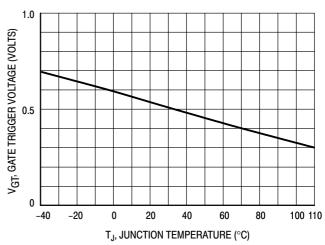


Figure 6. Typical Gate Trigger Voltage versus Junction Temperature

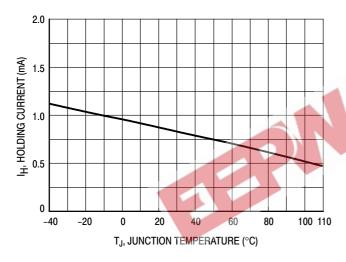


Figure 7. Typical Holding Current versus Junction Temperature

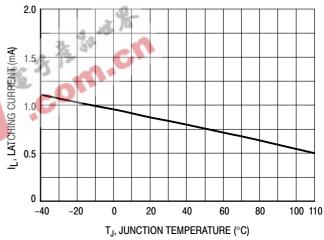
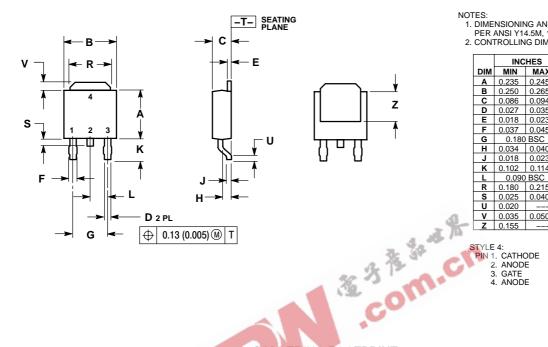


Figure 8. Typical Latching Current versus Junction Temperature

#### **PACKAGE DIMENSIONS**

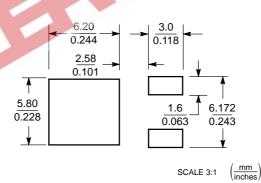
#### **DPAK** CASE 369C ISSUE O



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.22	
В	0.250	0.265	6.35	6.73	
C	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
Е	0.018	0.023	0.46	0.58	
F	0.037	0.045	0.94	1.14	
G	0.180 BSC		4.58 BSC		
Н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
K	0.102	0.114	2.60	2.89	
L	0.090 BSC		2.29 BSC		
R	0.180	0.215	4.57	5.45	
S	0.025	0.040	0.63	1.01	
כ	0.020		0.51		
٧	0.035	0.050	0.89	1.27	
Z	0.155		3.93		

#### **SOLDERING FOOTPRINT**





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